PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16571
1.3 Title of PCN	JSCC (China) Conversion of Glue to PFAS-free, on LFBGA10x10 listed products
1.4 Product Category	STM32F103ZxHx, STM32F103VxHx, STM32F105VxHx and STM32F107VxHx
1.5 Issue date	2026-10-26

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	Sherwood LIN
2.1.2 Phone	+86 13158864934
2.1.3 Email	sherwood.lin@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Die Attach Material - Chemistry/ Raw material	JSCC (China)

4. Description of change		
	Old	New
4.1 Description	PFAS glue 2025D	non-PFAS glue 2025DNP
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change	
5.1 Motivation	better supply service with the new glue
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change	
6.1 Description	traceability ensured by ST internal tools

7. Timing / schedule	
7.1 Date of qualification results	2026-12-15
7.2 Intended start of delivery	2027-01-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16571 RER2624 PCN16571 JSCC LFBGA10x10 conversion to PFAS free glue STM32 - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-10-26

9. Attachments (additional documentations)
16571 Public product.pdf 16571 RER2624 PCN16571 JSCC LFBGA10x10 conversion to PFAS free glue STM32 - reliability plan.pdf 16571 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F103ZFH6	

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Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : JSCC (China) Conversion of Glue to PFAS-free, on LFBGA10x10 listed products

PCN Reference : EMBEDDED PROCESSING/26/16571

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F103VDH6	STM32F103ZEH7TR	STM32F103ZCH6
STM32F103VEH7	STM32F103ZDH6TR	STM32F105VBH6
STM32F103ZEH6TR	STM32F105VBH6TR	STM32F107VCH6
STM32F103VEH6	STM32F103ZGH7	STM32F103VEH6TR
STM32F103ZEH7	STM32F103V8H6TR	STM32F103ZFH6TR
STM32F103V8H6	STM32F103VDH6TR	STM32F103VBH6
STM32F103ZGH6TR	STM32F103ZEH6	STM32F103VBH7
STM32F103VCH6	STM32F103ZDH6	STM32F103ZGH6
STM32F103ZFH6		

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PRODUCT/PROCESS CHANGE NOTIFICATION
PCN16571 – Additional information

JSCC (China) Conversion of Glue to PFAS-free, on LFBGA10x10 listed products.

MRDF - General Purpose and Automotive Microcontroller Division (GPAM)

What are the changes?

ST General Purpose Microcontrollers Division decided, in JSCC, to convert the LFBGA10x10 die attach to PFAS-free material. The objective is to strengthen the continuity of the supply service over time. The full process is maintaining state-of-the-art service level to our customers.

Changes are described in table below:

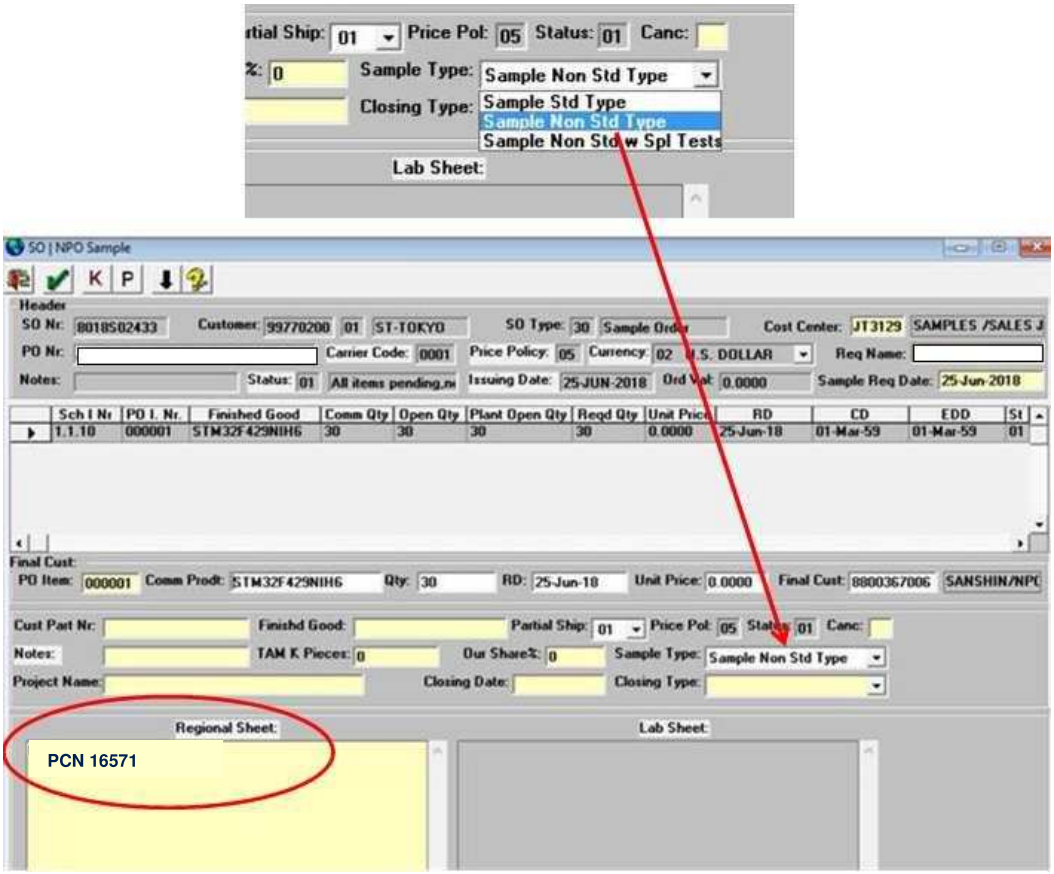
Table_1	Existing back-end assembly line	New assembly line
Assembly line	**StatsChipPAC JSCC Jiangyin (China)**	
Die Attach	2025D With PFAS*	2025DNP PFAS-Free
Marking	Without 2D	2D marking

(*) Current BOM (PFAS glue) will be discontinued at the end of 2026.

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN16571**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



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MDRF-GPAM-RER2624 PCN16571
JSCC LFBGA10x10 conversion to PFAS free

Reliability Evaluation Plan

16 Oct 2026

MDRF GPAM BE Q&R

MDRF-GPAM-RER2624 PCN
JSCC LFBGA10x10 conversion PFAS fre
Package Test Ve

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process/Plant	Number of Reliability Lots	Reliabili
BGA	LFBGA10x10	144L	X3*430	0.18/TSMC	3	Full reliabi

Qualification strategy:

- 3 full reliability lot needed to qualify new PFAS free glue Ablestik 2025DNP1 on JSCC LFBGA Au wire line

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MDRF-GPAM-RER2624 PCN
JSCC LFBGA10x10 conversion PFAS fre
Reliabilit

(*) tests performed after preconditioning

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Number of lot
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	179	3
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h	77	3
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy	77	3
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h	25	3
HTSL	High Temperature Storage Life JESD22 A103	150°C	1000h	77	3
Construction analysis	ST internal specification JESDB100/B108	POA, Ball shear, pull test, ST internal specification	NA	50	1
ESD	ESD Charge Device Model JEDEC JS-002	500V	No failure	3	1

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